



型号/TYPE : SLS4410

The 4410 is the high cell density trench N-ch MOSFETs, which provide excellent R_{DS(on)} and gate charge for most of the synchronous buck converter applications.

The 4410 meet the RoHS and Green Product requirement, 100% EAS guaranteed with full function reliability approved.

4410是高单元密度沟道n-ch mosfet，为大多数同步buck变换器应用提供了优良的rdson和栅极电荷。
4410符合RoHS和绿色产品要求，100%EAS保证，全功能可靠性得到认可。

主要特性/Features

N-CH 30V Fast Switching MOSFETs n-ch 30v快开关mosfet

Super Low Gate Charge 超低栅电荷

100% EAS Guaranteed 100%EAS保证

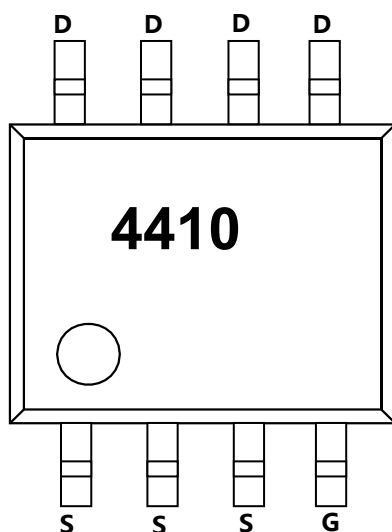
Excellent CdV/dt effect decline cdv/dt效应下降良好

Advanced high cell density Trench technology 先进的高密度槽技术

应用/Application

消费电子产品 Consumer electronics

印字/MARKING 引脚定义/pin definition





极限参数/N-Channel Absolute maximum ratings(Ta=25°C)

Symbol	Parameter	Rating	Units
V _{DS}	Drain-Source Voltage	30	V
V _{GS}	Gate-Source Voltage	±20	V
I _D @T _A =25°C	Continuous Drain Current, V _{GS} @ 10V ¹	15.0	A
I _D @T _A =70°C	Continuous Drain Current, V _{GS} @ 10V ¹	8.2	A
I _{DM}	Pulsed Drain Current ²	42	A
EAS	Single Pulse Avalanche Energy ³	61	mJ
I _{AS}	Avalanche Current	35	A
P _D @T _A =25°C	Total Power Dissipation ⁴	1.5	W
T _{STG}	Storage Temperature Range	-55 to 150	°C
T _J	Operating Junction Temperature Range	-55 to 150	°C

Thermal Data

Symbol	Parameter	Typ.	Max.	Unit
R _{θJA}	Thermal Resistance Junction-ambient ¹	---	85	°C/W
R _{θJC}	Thermal Resistance Junction-Case1	---	36	°C/W



电性能参数/ P-Channel Electrical characteristics (Ta=25°C)

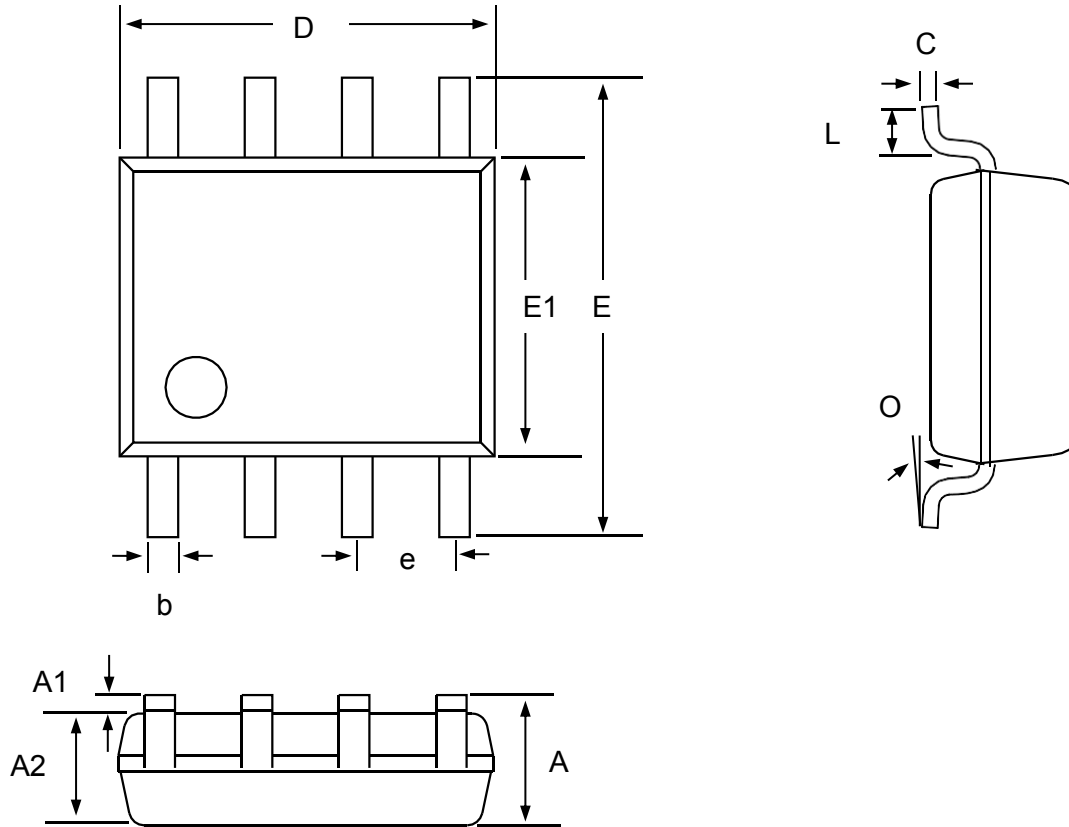
Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=250\mu A$	30	---	---	V
$\Delta BV_{DSS}/\Delta T_J$	BVDSS Temperature Coefficient	Reference to 25°C, $I_D=1mA$	---	0.027	---	V/°C
$R_{DS(ON)}$	Static Drain-Source On-Resistance ²	$V_{GS}=10V, I_D=10A$	---	7.5	9	mΩ
		$V_{GS}=4.5V, I_D=8A$	---	11	14	
$V_{GS(th)}$	Gate Threshold Voltage	$V_{GS}=V_{DS}, I_D=250\mu A$	1.2	1.5	2.5	V
$\Delta V_{GS(th)}$	VGS(th) Temperature Coefficient		---	-5.8	---	mV/°C
I_{DSS}	Drain-Source Leakage Current	$V_{DS}=24V, V_{GS}=0V, T_J=25^\circ C$	---	---	1	μA
		$V_{DS}=24V, V_{GS}=0V, T_J=55^\circ C$	---	---	5	
I_{GSS}	Gate-Source Leakage Current	$V_{GS}=\pm 20V, V_{DS}=0V$	---	---	±100	nA
g_{fs}	Forward Transconductance	$V_{DS}=5V, I_D=10A$	---	5.8	---	S
R_g	Gate Resistance	$V_{DS}=0V, V_{GS}=0V, f=1MHz$	---	2.2	3.8	
Q_g	Total Gate Charge (4.5V)	$V_{DS}=15V, V_{GS}=4.5V, I_D=10A$	---	12.6	17.6	nC
Q_{gs}	Gate-Source Charge		---	4.2	5.9	
Q_{gd}	Gate-Drain Charge		---	5.1	7.1	
$T_{d(on)}$	Turn-On Delay Time	$V_{DD}=15V, V_{GS}=10V, R_G=3.3, I_D=10A$	---	6.2	12.4	ns
T_r	Rise Time		---	59	106	
$T_{d(off)}$	Turn-Off Delay Time		---	27.6	55	
T_f	Fall Time		---	8.4	16.8	
C_{iss}	Input Capacitance	$V_{DS}=15V, V_{GS}=0V, f=1MHz$	---	1317	1845	pF
C_{oss}	Output Capacitance		---	163	228.2	
C_{rss}	Reverse Transfer Capacitance		---	131	183.4	

Diode Characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
I_S	Continuous Source Current ^{1,5}	$V_G=V_D=0V, \text{Force Current}$	---	---	10.3	A
I_{SM}	Pulsed Source Current ^{2,5}		---	---	42	A
V_{SD}	Diode Forward Voltage ²	$V_{GS}=0V, I_S=1A, T_J=25^\circ C$	---	---	1.2	V
t_{rr}	Reverse Recovery Time	$I_F=10A,$	---	12.5	---	nS
Q_{rr}	Reverse Recovery Charge	$dI/dt=100A/\mu s, T_J=25^\circ C$	---	5	---	nC



封装外观尺寸/SOP8 Package Information



Symbol	Dim in mm		
	Min	Nor	Max
A	1.350	1.550	1.750
A1	0.100	0.175	0.250
A2	1.350	1.450	1.550
b	0.330	0.420	0.510
c	0.170	0.210	0.250
D	4.800	4.900	5.000
e	1.270(BSC)		
E	3.800	3.900	4.000
E1	0.400	0.835	1.2700
L	0°	4°	8°